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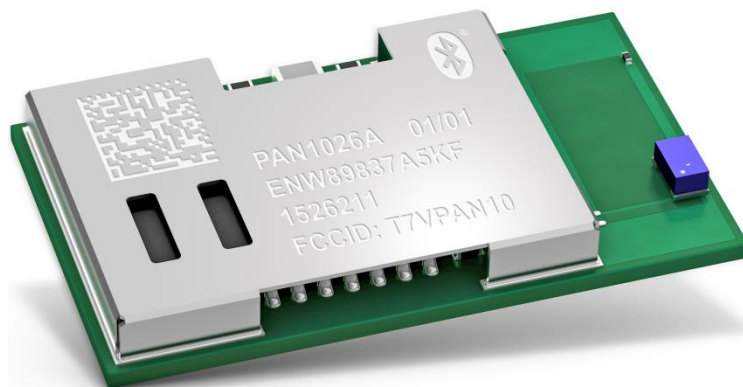
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PAN1026A

Bluetooth Basic Data Rate and Low Energy Module Product Specification

Rev. 0.1



Overview

The PAN1026A is a Class 2 Bluetooth 4.2 Basic Data Rate and Low Energy module for easy implementation of Bluetooth functionality into various electronic devices.

Features

- Bluetooth 4.2 Basic Data Rate (BR) and Low Energy (LE)
- Embedded SPP profile
- Embedded GATT profile
- High-level API commands
- Bluetooth 4.2 (LE) embedded GATT profile with high-level API commands, compatible with Toshiba reference BLE profiles
- Operational temperature range -40 to +85 °C
- Operational voltage 2.7 V to 3.6 V +/- 10 %
- Power consumption Tx: 46 mA
- Dimensions 15.6 x 8.7 x 1.9 mm
- Output power 4 dBm
- -88 dBm sensitivity
- Integrated high speed crystal oscillator (26 MHz)

New Features

- Increased (2.5 x) BLE data transfer rates through extended MTU size (64 bytes to 160 bytes)
- More complex BLE profiles possible through extended GATT functionality
- Data base pool, number of services and characteristics, data flow control
- Fast SPP classic connection/disconnection times
- Interlaced inquiry/page scan & extended inquiry response
- Transmission (Tx) power control
- Improved PER (peak-error-rate) for BLE traffic
- Integration of BT 4.2 secure connecting feature implementing ECDH technology

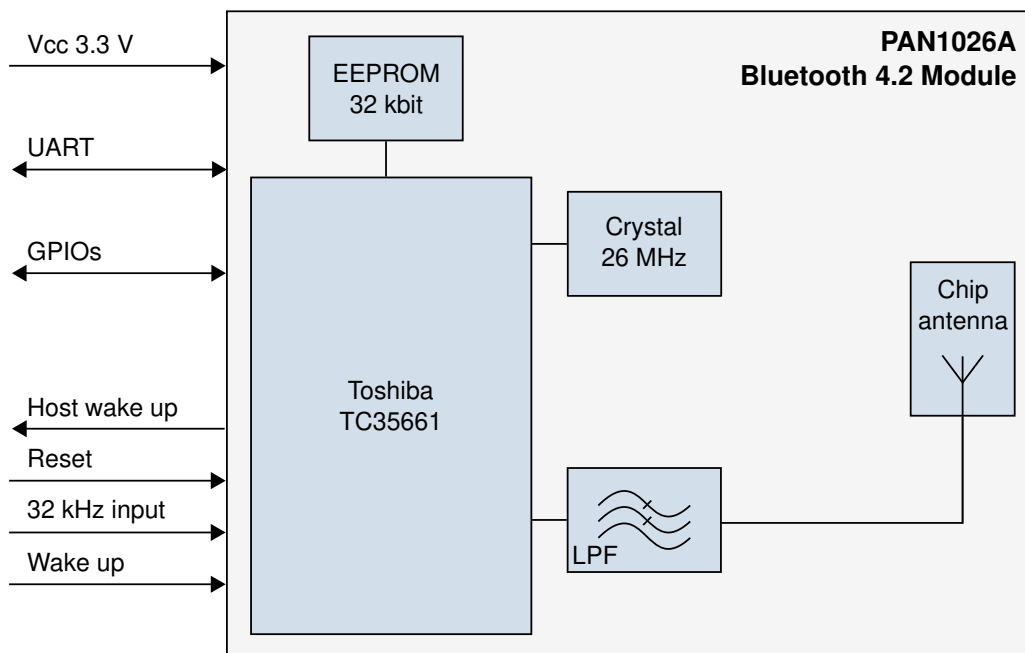
Bluetooth

- GAP support for SPP
- GAP Peripheral and Broadcast support for LE
- GATT server and client mode support for LE
- GAP Central and Observer not supported for LE

Interfaces

- UART, GPIO (10 input/output pins), wake-up control pins

Block Diagram



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1 About This Document



1.1 Purpose and Audience

This Product Specification provides details on the functional, operational, and electrical characteristics of the Panasonic PAN1026A module. It is intended for hardware design, application, and Original Equipment Manufacturers (OEM) engineers. The product is referred to as “the PAN1026A” or “the module” within this document.

1.2 Revision History

Revision	Date	Modifications/Remarks
0.1	23.03.2017	1st preliminary version.

1.3 Use of Symbols

Symbol	Description
	Note Indicates important information for the proper use of the product. Non-observance can lead to errors.
	Attention Indicates important notes that, if not observed, can put the product's functionality at risk.
⇒ [chapter number] [chapter title]	Cross reference Indicates crossreferences within the document. Example: Description of the symbols used in this document ⇒ 1.3 Use of Symbols.

1.4 Related Documents

Please refer to the Panasonic website for related documents ⇒ [7.2.2 Product Information](#).

2 Overview

The PAN1026A is based on Toshiba's single-chip TC35661 Bluetooth semiconductor device with an embedded Toshiba Bluetooth SIG certified stack. The PAN1026A is a highly integrated Dual Mode Bluetooth controller that delivers high-speed operation at ultra-low power consumption. An embedded SPP (Serial Port Profile of Bluetooth Classic) and a GATT (Generic Attribute Profile of Bluetooth LE) stack are integrated. The module significantly reduces external component count and power consumption in applications requiring support of Bluetooth 4.2 standards. EDR (Enhanced Data Rate) or Central Mode are not supported. Details about iAP integration can be provided on request. The integrated EEPROM has a Panasonic MAC address and it can be used to store link keys.

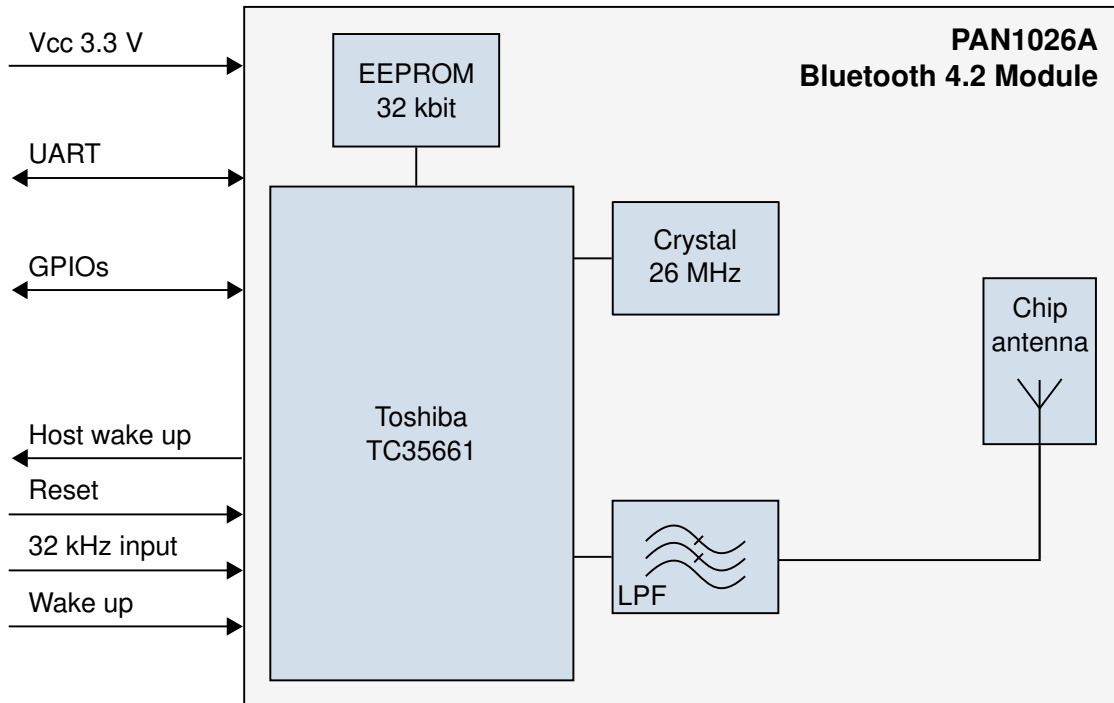
The module allows for serving both legacy Bluetooth Classic and Bluetooth Low Energy connections with rapid connection and disconnection, needed by a wide range of applications, all at a small form factor. Compared to the PAN1026, the PAN1026A has additional features for secure connections via Bluetooth LE and it is fully backwards compatible. Next to increased low energy transfer speed, transmission power can also be controlled.

The PAN1026A module is manufactured in a small 15.6 x 8.7 x 1.9 mm SMD package with a shielded case and it is qualified according to the Bluetooth 2.1 and 4.2 standards.

Please refer to the Panasonic website for related documents ⇒ [7.2.2 Product Information](#).

Further information on the variants and versions ⇒ [7.1 Ordering Information](#).

2.1 Block Diagram

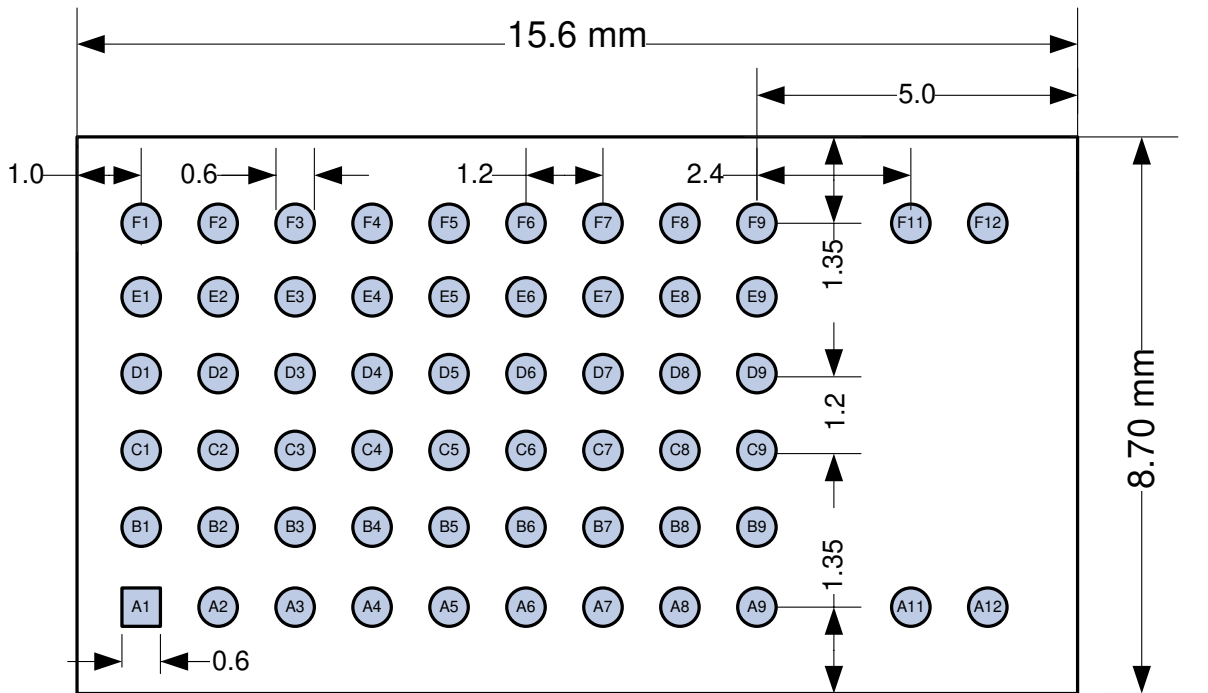


Total capacitor value: 6.7 μF +/-10 %
 Total inductance: 2 nH +/-10 %
 Total resistance: 220 k Ω +/-10 %

2.2 Pin Configuration

Pin Assignment

Top View



Pin Functions

No	Pin Name	GPIO No	Pin Type	Description
A1	GND		Ground Pin	Connect to ground
A2	NC		NC	Not connected, leave open
A3	Reset		Digital Input	Reset, active low
A4	VCC		Power	analog/digital power supply connection
A5	VCC		Power	analog/digital power supply connection
A6	VCC		Power	analog/digital power supply connection
A7	GND		Ground Pin	Connect to ground
A8	NC		NC	Not connected
A9	GND		Ground Pin	Connect to ground
A11	GND		Ground Pin	Connect to ground
A12	GND		Ground Pin	Connect to ground

No	Pin Name	GPIO No	Pin Type	Description
B1	NC		NC	Not connected, leave open
B2	BTS	GPIO 11		
B3	BTA	GPIO 10		
B4	NC		NC	Not connected, leave open
B5	NC		NC	Not connected, leave open
B6	NC		NC	Not connected, leave open
B7	NC		NC	Not connected, leave open
B8	NC		NC	Not connected, leave open
B9	NC		NC	Not connected, leave open
C1	CS0X	GPIO 17		
C2	BTI	GPIO 13		
C3	WIA	GPIO 12		
C4	NC		NC	Not connected, leave open
C5	NC		NC	Not connected, leave open
C6	PCMCLK	GPIO 04	Digital I/O	PCM clock
C7	FSYNC	GPIO 05	Digital I/O	PCM synchronization
C8	GND		Ground Pin	Connect to ground
C9	GND		Ground Pin	Connect to ground
D1	CS1X	GPIO 18		
D2	DIN	GPIO 16		
D3	GPIO1	GPIO 01	Digital I/O	
D4	GPIO0		Digital I/O	
D5	NC		NC	Not connected, leave open
D6	PCMIN	GPIO 03	Digital Input	PCM In: Not supported
D7	GND		Ground Pin	Connect to ground
D8	GND		Ground Pin	Connect to ground
D9	ANT		RF-Signal	Antenna pin (not connected for standard version)
E1	SDA	GPIO 15	Digital I/O	I2C interface (only internal), connect to test pin
E2	SCL	GPIO 14	Digital I/O	I2C interface (only internal), connect to test pin
E3	GND		Ground Pin	Connect to ground
E4	USB			USB direct is not supported by the IC. Leave this pin open.
E5	CLKREQ		Digital Output	Active high once crystal frequency is stable
E6	UART RXD		Digital Input	UART RXD

No	Pin Name	GPIO No	Pin Type	Description
E7	PCMOUT	GPIO 02	Digital Output	PCM Output: not supported
E8	GND		Ground Pin	Connect to ground
E9	GND		Ground Pin	Connect to ground
F1	GND		Ground Pin	Connect to ground
F2	EEPROM_WP		Digital Input	Internal EEPROM Write Protect (active high)
F3	GND		Ground Pin	Connect to ground
F4	GND		Ground Pin	Connect to ground
F5	UART CTS		Digital Input	UART CTS
F6	SLEEPCLK		Digital Input	Input clock for 32.768 KHz
F7	UARTTXD		Digital Output	UART TX
F8	UARTRTS		Digital Output	UART RTS
F9	GND		Ground Pin	Connect to ground
F11	GND		Ground Pin	Connect to ground
F12	GND		Ground Pin	Connect to ground

2.3 UART Interface


- Full-duplex 4-wire data transfer: RX, TX, RTS, CTS
- Programmable baud rate: 2 400 bps to 4.33 Mbps
- Default baud rate: 115 200 bps
- Data format: 8N1, LSB first
- Error detection: Character timeout, Overrun error, Framing error

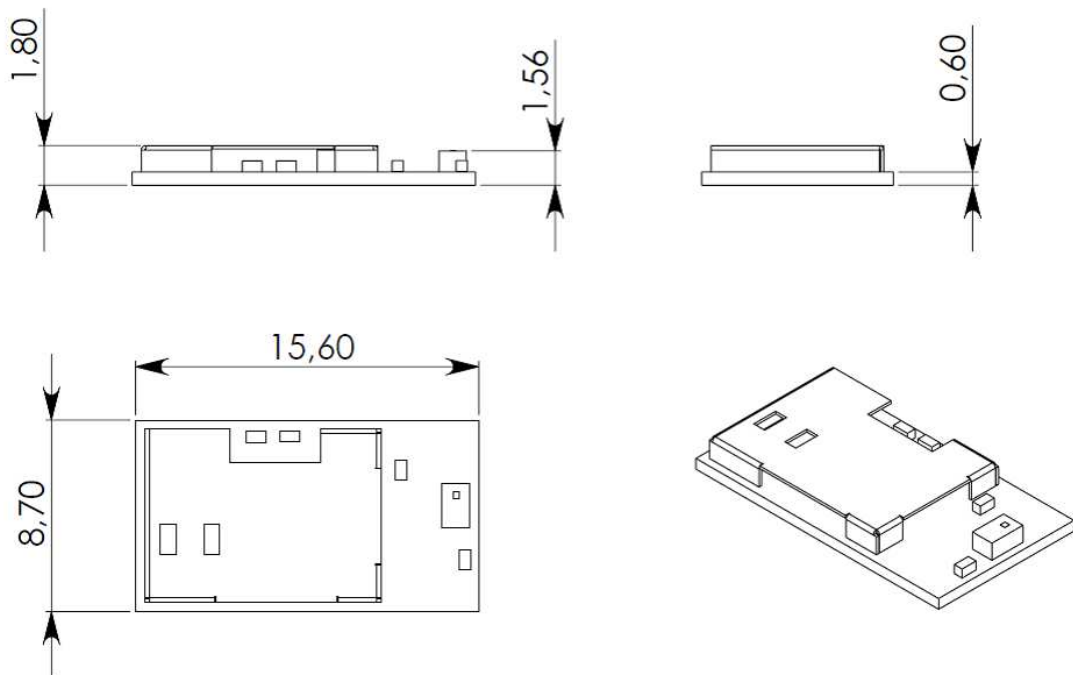
2.4 Bluetooth Features

- Bluetooth 4.0 with SPP & GATT
- GAP support for SPP
- GATT server and client mode supported for LE
- Class 2 TX power w/o external PA (improved link robustness)
- Excellent link budget (up to 91 dB), enabling long-range applications
- GAP peripheral support for LE

3 Detailed Description

3.1 Dimensions

 All dimensions are in millimeters.

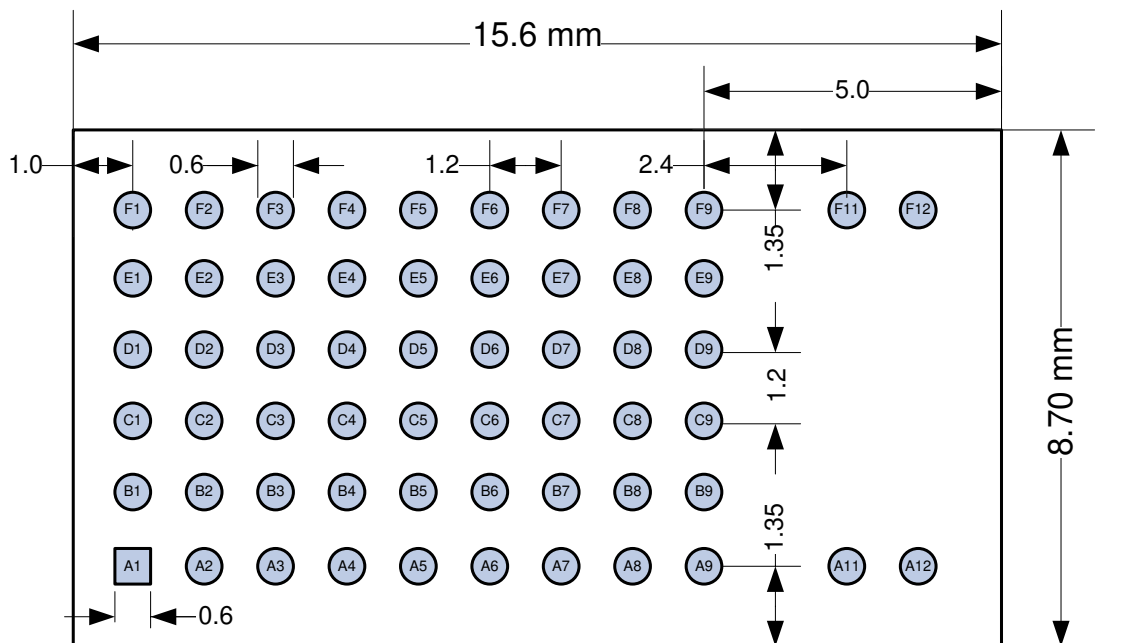


No.	Item	Dimension	Tolerance	Remark
1	Width	8.70	± 0.20	
2	Length	15.60	± 0.20	
3	Height	1.80	± 0.20	With case

3.2 Footprint

 The outer dimensions have a tolerance of ± 0.3 mm.

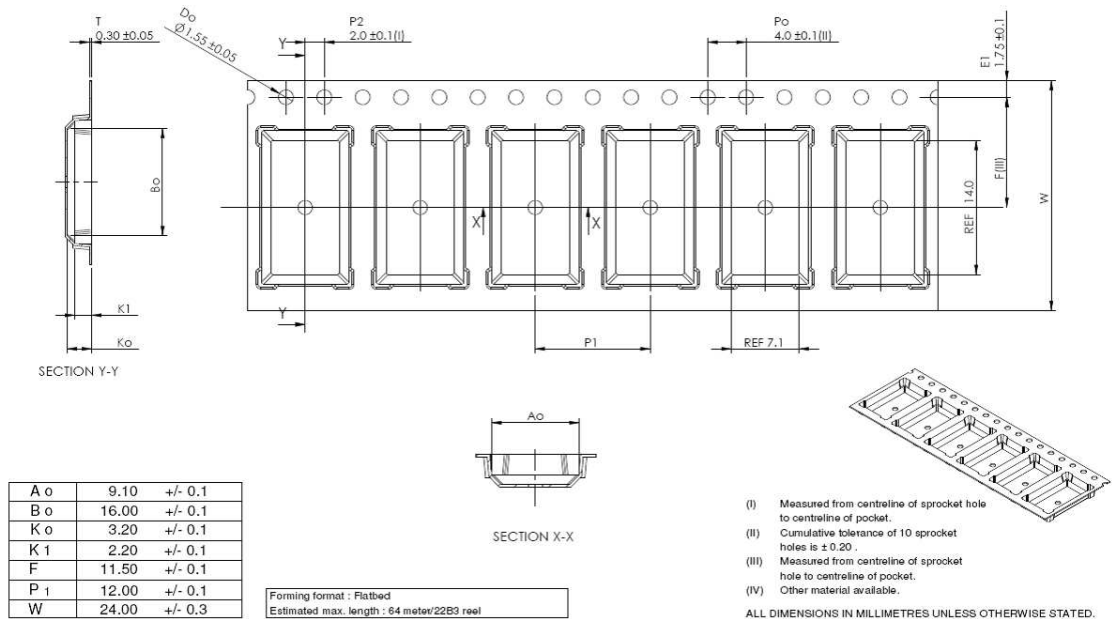
Top View



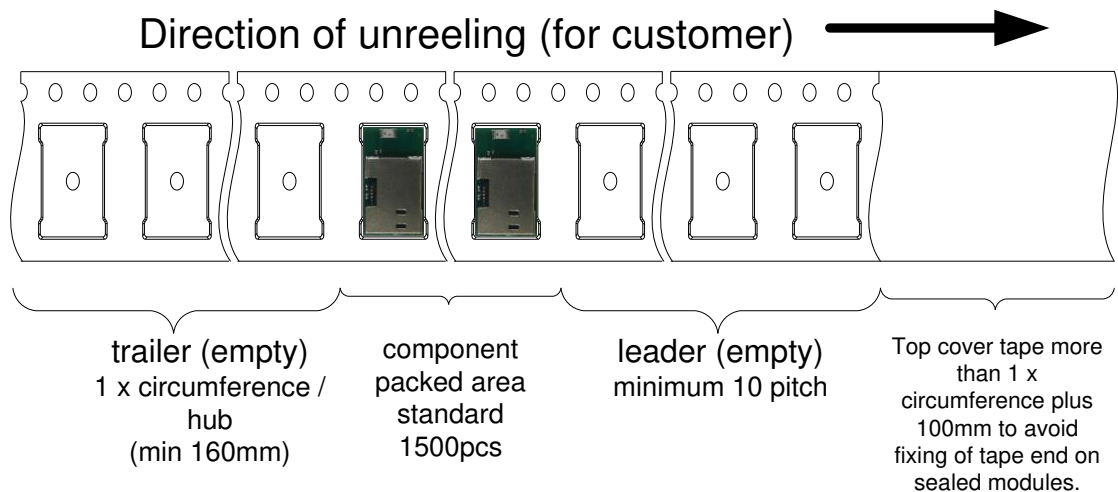
3.3 Packaging

The product is a mass production status product and will be delivered in the package described below.

3.3.1 Tape Dimensions



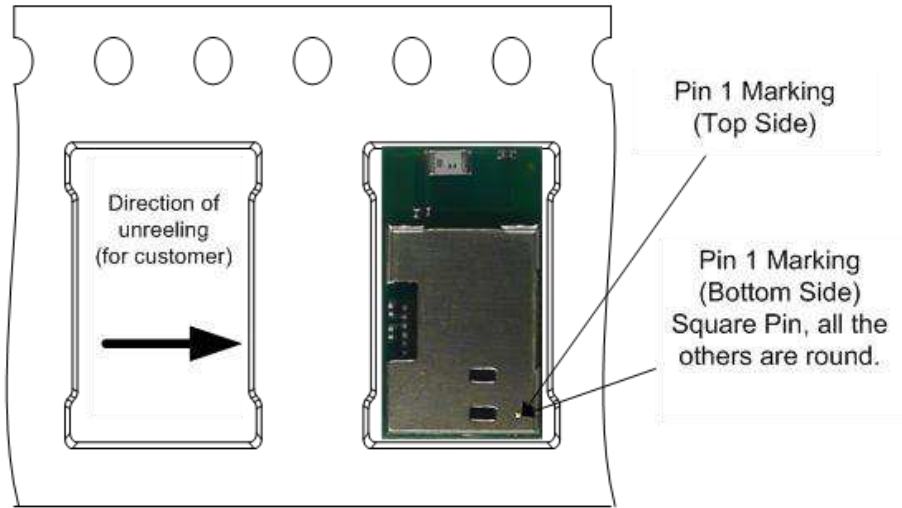
3.3.2 Packing in Tape



Empty spaces in the component packed area shall be less than two per reel and those spaces shall not be consecutive.

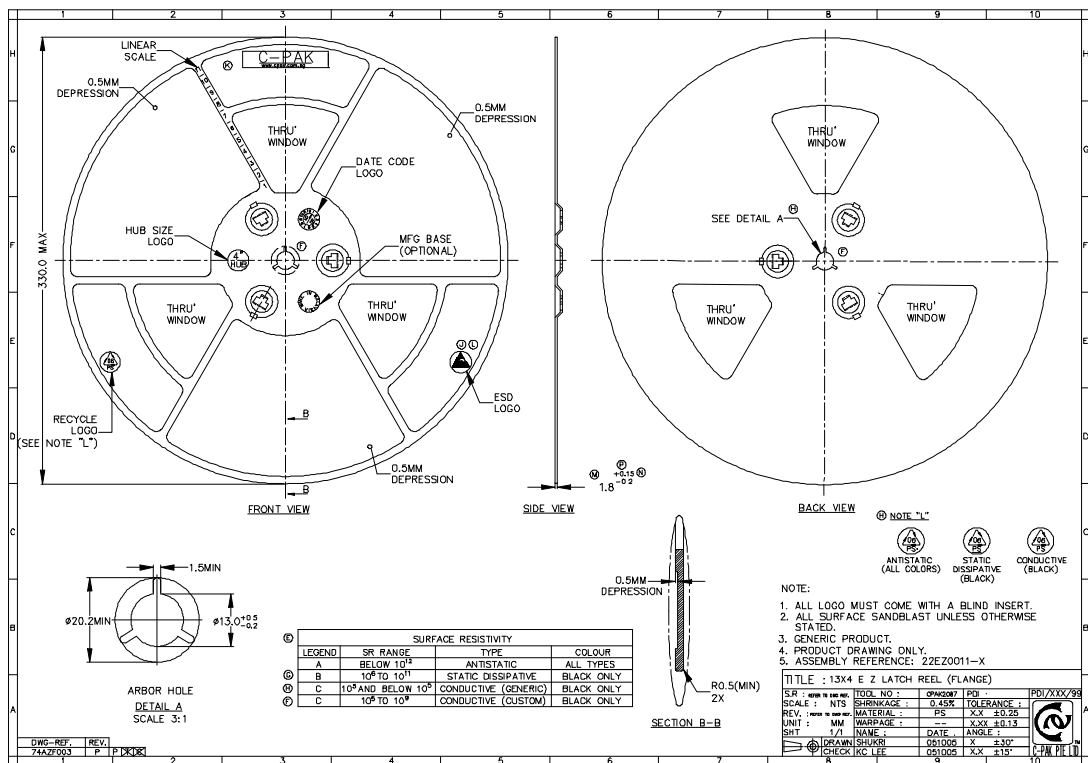
The top cover tape shall not be found on reel holes and it shall not stick out from the reel.

3.3.3 Component Direction



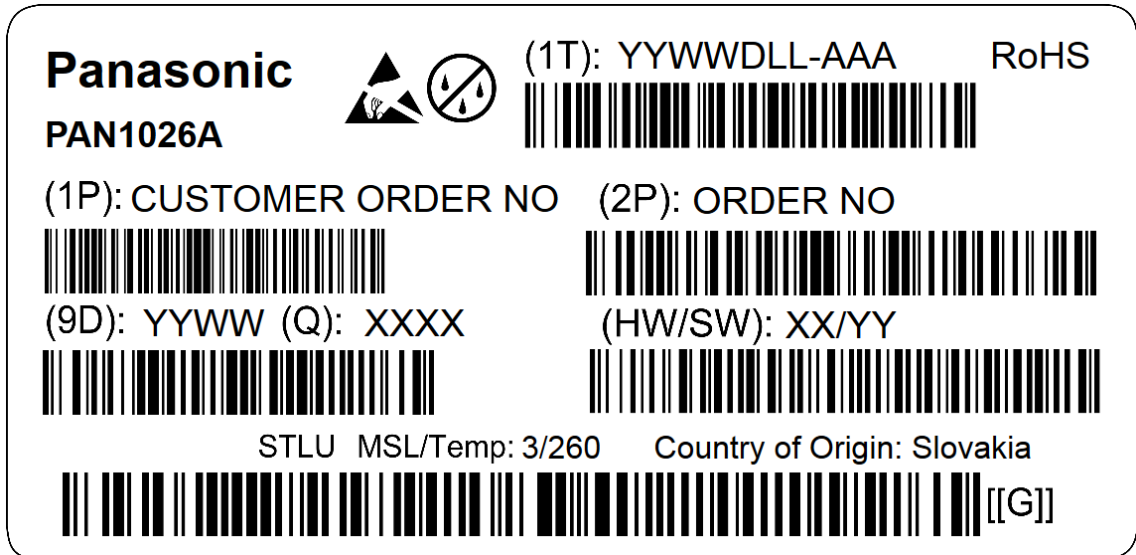
100730-PAN1720.vsd

3.3.4 Reel Dimension



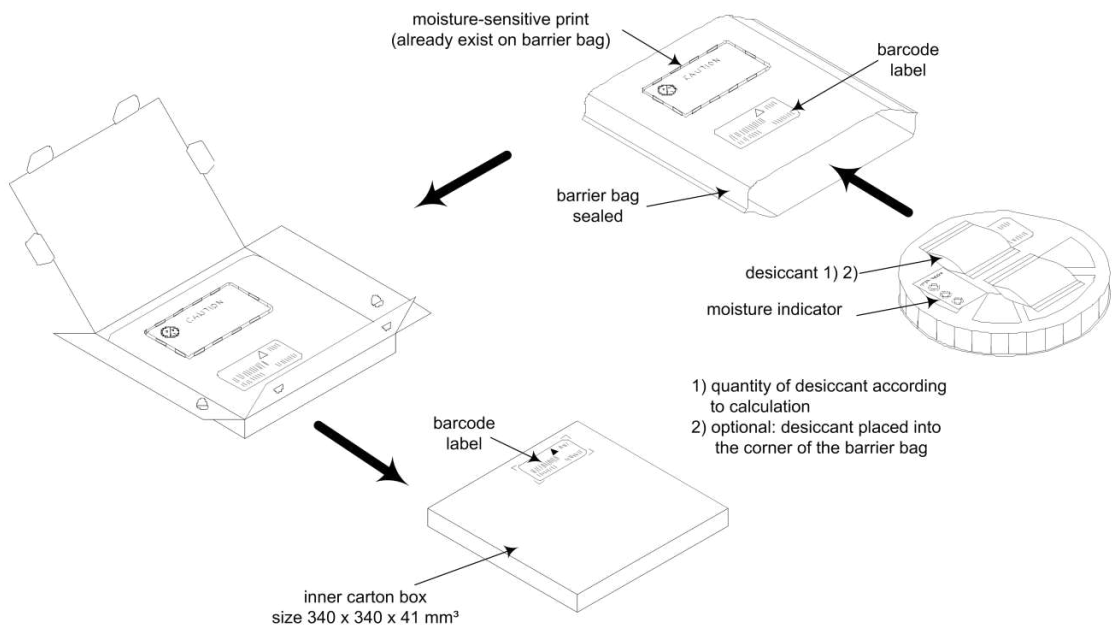
3.3.5 Package Label

Example



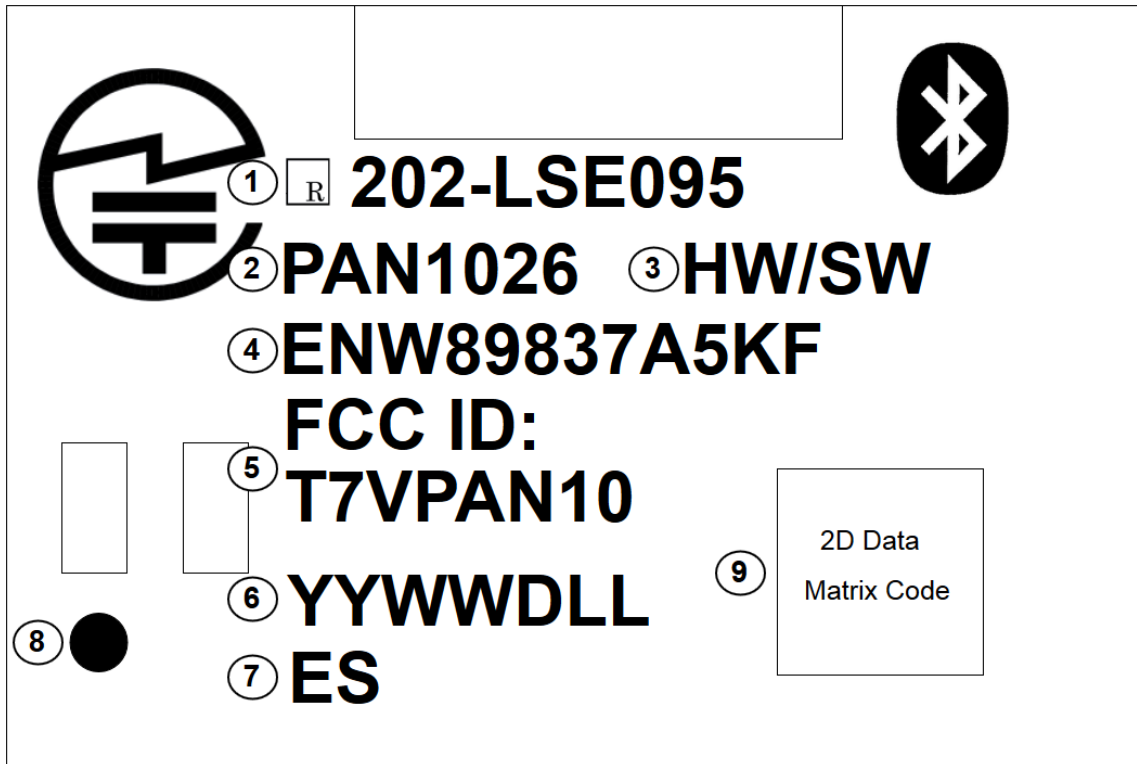
(1T)	Lot code
(1P)	Customer order number, if applicable
(2P)	Order number
(9D)	Date code
(Q)	Quantity
(HW/SW)	Hardware/software version

3.3.6 Total Package



3.4 Case Marking

Example



1	MIC ID
2	Brand name
3	Hardware/software version
4	Order number
5	FCC ID
6	Lot code
7	Engineering Sample marking, if applicable
8	Marking for Pin 1
9	2D barcode, for internal usage only

4 Specification



All specifications are over temperature and process, unless indicated otherwise.

4.1 Default Test Conditions



Temperature: 25 ± 10 °C
 Humidity: 40 to 85 % RH
 Supply Voltage: 3.3 V

4.2 Absolute Maximum Ratings



The maximum ratings may not be exceeded under any circumstances, not even momentarily or individually, as permanent damage to the module may result.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
T _{STOR}	Storage temperature		-40		+125	°C
V _{ESD}	ESD robustness	All pads, according to human body model (HBM), JEDEC STD 22, method A114			1 000	V
		According to charged device model (CDM), JEDEC STD 22, method C101			500	V
P _{RF}	RF input level				+10	dBm
V _{DIG}	Voltage on any digital pins		-0.3		VDD + 0.3	V

4.3 Recommended Operating Conditions



The maximum ratings may not be exceeded under any circumstances, not even momentarily or individually, as permanent damage to the module may result.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
T _A	Ambient operating temperature range		-40		+85	°C
V _{DD}	3V3 Supply voltage		2.7	3.3	3.6	V

4.4 Current Consumption



The current consumption depends on the user scenario and on the setup and timing in the power modes.

Assume V_{DD} = 3.3 V, T_{amb} = 25 °C, if nothing else stated.

Parameter	Condition	Min.	Typ.	Max.	Units
Idle Current	After reset was pulled down.		7.8		mA
Connected Peak Power	Sending DH5 packets. Max. output power.			62	mA
Connected Peak Power	Sending DH3 packets. Max. output power.			61	mA
Connected Peak Power	Sending DH1 packets. Max. output power.			55	mA
Sleep mode activated	Sniff mode/not connected/BLE Advertising		2		mA

4.5 Bluetooth

Parameter	Condition	Min.	Typ.	Max.	Units
Operation frequency range		2 402		2 480	MHz
Channel spacing	BT-Classic/BLE		1/2		MHz
Output Power	Maximum setting, measured at dual ended 50 ohm.		4		dBm
Sensitivity			-88		dBm


Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
1	Spurious emissions	Conducted measurement with a 50 Ω dual-ended load. Complies with EN 300 328, EN 300 440 class 2, FCC CFR47, Part 15 and ARIB STD-T-66.		<-30		dBm

4.6 Reliability Tests

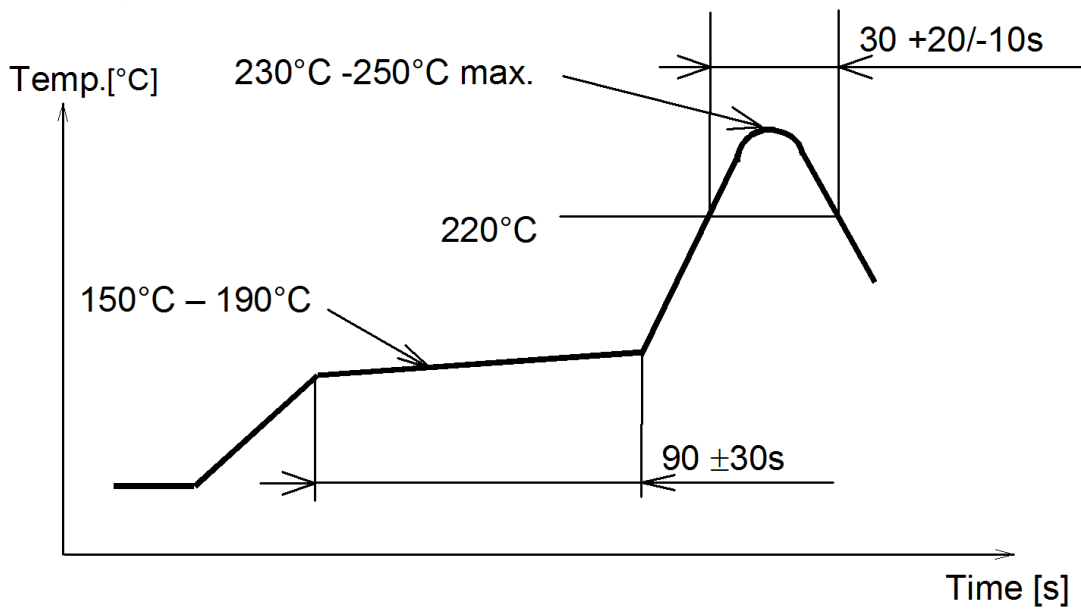
The measurement should be done after the test device has been exposed to room temperature and humidity for one hour.

No.	Item	Limit	Condition
1	Vibration test	Electrical parameter should be in specification	<ul style="list-style-type: none"> • Freq.: 10~50 Hz; Amplitude: 1.5 mm; 20 min./cycle, 1 hrs. each of XYZ axis • Freq.: 30~100 Hz, 6G; 20 min./cycle, 1 hrs. each of XYZ axis
2	Shock test	See above	Dropped onto hard wood from a height of 50 cm for 3 times
3	Heat cycle test	See above	-40 °C for 30 min. and +85 °C for 30 min.; each temperature 300 cycles
4	Moisture test	See above	+60 °C, 90 % RH, 300 h
5	Low temperature test	See above	-40 °C, 300 h
6	High temp. test	See above	+85 °C, 300 h

4.7 Recommended Soldering Profile



- Reflow permissible cycle: 2
- Opposite side reflow is prohibited due to module weight
- More than 75 percent of the soldering area shall be coated by solder
- The soldering profiles should be adhered to in order to prevent electrical or mechanical damage
- Soldering profile assumes lead-free soldering



5 Cautions



Failure to follow the guidelines set forth in this document may result in degrading of the product's functions and damage to the product.

5.1 Design Notes

1. Follow the conditions written in this specification, especially the control signals of this module.
2. The supply voltage must be free of AC ripple voltage (for example from a battery or a low noise regulator output). For noisy supply voltages, provide a decoupling circuit (for example a ferrite in series connection and a bypass capacitor to ground of at least 47 μ F directly at the module).
3. This product should not be mechanically stressed when installed.
4. Keep this product away from heat. Heat is the major cause of decreasing the life of these products.
5. Avoid assembly and use of the target equipment in conditions where the product's temperature may exceed the maximum tolerance.
6. The supply voltage should not be exceedingly high or reversed. It should not carry noise and/or spikes.
7. Keep this product away from other high frequency circuits.
8. Refer to the recommended pattern when designing a board.

5.2 Installation Notes

1. Reflow soldering is possible twice based on the conditions set forth in [⇒ 4.7 Recommended Soldering Profile](#). Set up the temperature at the soldering portion of this product according to this reflow profile.
2. Carefully position the products so that their heat will not burn into printed circuit boards or affect the other components that are susceptible to heat.
3. Carefully locate these products so that their temperatures will not increase due to the effects of heat generated by neighboring components.
4. If a vinyl-covered wire comes into contact with the products, then the cover will melt and generate toxic gas, damaging the insulation. Never allow contact between the cover and these products to occur.
5. This product should not be mechanically stressed or vibrated when reflowed.
6. To repair the board by hand soldering, follow the conditions set forth in this chapter.
7. Do not wash this product.
8. Pressing on parts of the metal cover or fastening objects to the metal will cause damage to the unit.

5.3 Usage Condition Notes

1. Take measures to protect the unit against static electricity.
If pulses or other transient loads (a large load applied in a short time) are applied to the products, check and evaluate their operation before assembly on the final products.
2. Do not use dropped products.
3. Do not touch, damage or soil the pins.
4. Follow the recommended condition ratings about the power supply applied to this product.
5. Electrode peeling strength: Do not add pressure of more than 4.9 N when soldered on PCB.
6. Pressing on parts of the metal cover or fastening objects to the metal cover will cause damage.
7. These products are intended for general purpose and standard use in general electronic equipment, such as home appliances, office equipment, information, and communication equipment.

5.4 Storage Notes

1. The module should not be stressed mechanically during storage.
2. Do not store these products in the following conditions or the performance characteristics of the product, such as RF performance will be adversely affected:
 - Storage in salty air or in an environment with a high concentration of corrosive gas, such as Cl₂, H₂S, NH₃, SO₂, or NO_x,
 - Storage in direct sunlight,
 - Storage in an environment where the temperature may be outside the range of 5 °C to 35 °C, or where the humidity may be outside the 45 to 85 percent range,
 - Storage of the products for more than one year after the date of delivery storage period: Please check the adhesive strength of the embossed tape and soldering after 6 months of storage.
3. Keep this product away from water, poisonous gas, and corrosive gas.
4. This product should not be stressed or shocked when transported.
5. Follow the specification when stacking packed crates (max. 10).

5.5 Safety Cautions

These specifications are intended to preserve the quality assurance of products and individual components.

Before use, check and evaluate the operation when mounted on your products. Abide by these specifications without deviation when using the products. These products may short-circuit. If electrical shocks, smoke, fire, and/or accidents involving human life are anticipated when a short circuit occurs, provide the following failsafe functions as a minimum:

1. Ensure the safety of the whole system by installing a protection circuit and a protection device.
2. Ensure the safety of the whole system by installing a redundant circuit or another system to prevent a single fault causing an unsafe status.

5.6 Other Cautions

1. Do not use the products for other purposes than those listed.
2. Be sure to provide an appropriate fail-safe function on your product to prevent any additional damage that may be caused by the abnormal function or the failure of the product.
3. This product has been manufactured without any ozone chemical controlled under the Montreal Protocol.
4. These products are not intended for uses other than under the special conditions shown below. Before using these products under such special conditions, carefully check their performance and reliability under the said special conditions to determine whether or not they can be used in such a manner:
 - In liquid, such as water, salt water, oil, alkali, or organic solvent, or in places where liquid may splash.
 - In direct sunlight, outdoors, or in a dusty environment.
 - In an environment where condensation occurs.
 - In an environment with a high concentration of harmful gas (e. g. salty air, HCl, Cl₂, SO₂, H₂S, NH₃, and NO_x).
5. If an abnormal voltage is applied due to a problem occurring in other components or circuits, replace these products with new products because they may not be able to provide normal performance even if their electronic characteristics and appearances appear satisfactory.
6. When you have any question or uncertainty, contact Panasonic.

5.7 Life Support Policy

This Panasonic Industrial Devices Europe GmbH product is not designed for use in life support appliances, devices, or systems where malfunction can reasonably be expected to result in a significant personal injury to the user, or as a critical component in any life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

Panasonic customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Panasonic Industrial Devices Europe GmbH for any damages resulting.

6 Regulatory and Certification Information

6.1 RoHS and REACH Declaration

The latest declaration of environmental compatibility (Restriction of Hazardous Substances, RoHS and Registration, Evaluation, Authorisation, and Restriction of Chemicals, REACH) for supplied products can be found on the Panasonic website in the “Downloads” section of the respective product ⇒ [7.2.2 Product Information](#).

6.2 Further Regulatory Information

To be discussed.

7 Appendix

7.1 Ordering Information

Variants and Versions

Order Number	Brand Name	Description	MOQ ¹
ENW89837A5KF ²	PAN1026A	Bluetooth BT4.2 Basic Data Rate and Low Energy module	1 500

¹ Abbreviation for Minimum Order Quantity (MOQ). The default MOQ for mass production is 1 500 pieces, fewer only on customer demand. Samples for evaluation can be delivered at any quantity via the distribution channels.

² Samples are available on customer demand.